

connected to the leads, wherein the substrate main body includes a plurality of through-holes, internal surfaces of the through-holes are conductive and connected to respective leads, such that as the substrate main body is cut along predetermined through-holes, remaining through-holes of the substrate main body define the conduction sections.

7. (Three Times Amended) A semiconductor apparatus, comprising:

a semiconductor device having a plurality of electrodes;

a substrate main body;

a plurality of leads formed on the substrate main body, the plurality of leads radially extending from a peripheral area toward a central area of the substrate main body; and

a plurality of conduction sections formed on the substrate main body with substantially rectangular contour lines, the conduction sections being electrically connected to the leads, and one of the conduction sections defining an external terminal, wherein the substrate main body includes a plurality of through-holes, internal surfaces of the through-holes are conductive and connected to respective leads, such that as the substrate main body is cut along predetermined through-holes, remaining through-holes of the substrate main body define the conduction sections.

REMARKS

Claims 1, 3-4, 6-7 and 9-12 are pending in this application. By this Amendment, claims 2, 8, 11 and 19-25 are canceled without prejudice or disclaimer, and claims 1 and 7 are amended. Reconsideration of the application in view of the above amendments and the following remarks is respectfully requested.

The attached Appendix includes a marked-up copy of each rewritten claim (37 C.F.R. §1.121(c)(1)(ii)).